ROYALOHM

' O N F I D E N T I A L D O C U M E N '

SPECIFICATION FOR APPROVAL

TRELIK

Description: Thick Film Chip Resistor Array (Terminal Lead Free)

Royalohm Part no.:

2D02WGJxxxxTCE (RMC 1/16W (2D02) +/- 5% T/R-10,000)

Approved by					

Parts corresponding to RoHS Compliant: 2005-Apr.-1

Royal Electronic Factory (Thailand) Co., Ltd.

20/1-2 Moo 2 Klong-Na, Muang

Chachoengsao 24000, Thailand

Tel: +66-38-822404-8

Fax: +66 38-981190 / 823765

E-mail Address: Export sales: Export@royalohm.com

Local sales: Local@royalohm.com

http://www.royalohm.com

P.O. Box 251 Klongchan, Bangkok 10240, Thailand

Approved	Checked	Prepared
Mr. Jack Lin	Mr. S. Polthanasan	Ms. P. Supatta

Issued Date: 2015/01/12

	CHANGE NOTIFICATION HISTORY							
Version	Date of Version	History	Remark					
1	2015/01/12	Resistance Range: $10\Omega \sim 1M\Omega$						

Customer: TRELIK Part No.: 2D02WGJxxxxTCE

1. Scope:

This specification for approval relates to Thick Film Chip Resistor Array (Terminal Lead Free) manufactured by ROYALOHM's specifications.

2. Type designation:

The type designation shall be in the following form:

Ex.

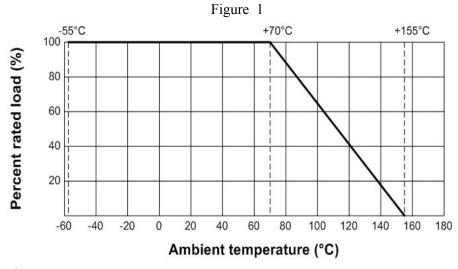
Type	Power Rating	Resistance tolerance	Nominal Resistance
RMC 2D02	1/16W	J	10ΚΩ

3. Ratings:

Туре	RMC 2D02
Power Rating	0.0625W (1/16W)
Max. Working Voltage	50 V
Max. Overload Voltage	100 V
Dielectric Withstanding Voltage	100 V
Temperature Range	-55°C ~ +155°C
Ambient Temperature	70 ℃
Resistance Tolerance	± 5 %
Resistance Range	$10\Omega\sim 1M\Omega$

3.1 Power rating:

Resistors shall have a power rating based on continuous load operation at an ambient temperature of 70 $^{\circ}$ C . For temperature in excess of 70 $^{\circ}$ C , The load shall be derate as shown in figure 1.

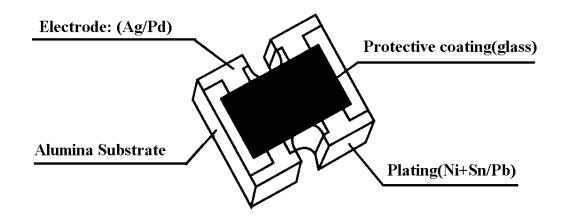


3.2 Nominal Resistance

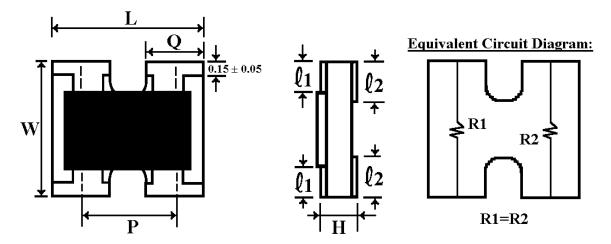
Effective figures of nominal resistance shall be in accordance with E-24 and E-96 series for 1 % and E-24 series for 2 % and 5 %

Thick Film Chip Resistor Array (Terminal Lead Free)

4. Construction:



5. Power rating and dimensions



Dimension:

	Dimension (mm)								
Туре	L ± 0.10	W + 0.10	H ± 0.10	ℓ1 ± 0.10	ℓ2 ± 0.10	P ± 0.05	Q ± 0.1		
RMC 2D02	1.00	1.00	0.35	0.17	0.25	0.65	0.33		

Power Rating:

Туре	Power Rating	Tolerance	Resistance	Standard	
	at 70 °C	%	Range	Resistance values	
RMC 2D02	0.0625 W (1/16W)	± 5	$10\sim 1M\Omega$	E-24	

Thick Film Chip Resistor Array (Terminal Lead Free)

6. Marking:

- 6.1 Resistors
 - *Thick Film Chip Resistor Array type 2D02 No marking
- 6.2 Labels

Label shall be marked with the following item:

- A. Nominal Resistance and Resistance Tolerance
- B. Power Rating and Size
- C. Quantity
- D. Part No.
- E. P.O.No.
- F. Lot No.

Ex.

ROYALOHM CHIP RESISTOR

RESISTANCE: 1K 5 % Ω ±

SIZE:

2D02

1/16W QUANTITY: 10,000 **PCS**

PART NO.:

P.O.NO.:

WATTAGE:

LOT NO.: 6050008 2D02WGJ0103TCE

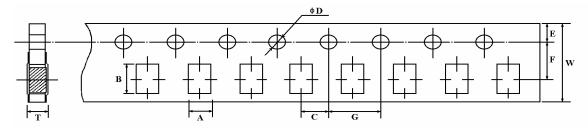
	Thick Film Chip Re	esistor Array (Lead Free)				
7. Performan	ce specification :					
Characteristics	Limits	Test Methods (JIS C 5201-1)				
Insulation resistance	1,000 M Ω or more	4.6 Apply 500V DC between protective coating and termination for 1 min, then measure				
Dielectric withstanding	No evidence of flashover mechanical damage, arcing or insulation break down	4.7 Apply 500V AC between protective coating and termination for 1 minute				
Temperature coefficient	± 200 PPM/°C	4.8 Natural resistance change per temp. degree centigrade. R2-R1 x 10 ⁶ (PPM/°C) R1(t2-t1) R1: Resistance value at room temperature (t1) R2: Resistance value at room temp. plus 100 °C (t2)				
Short time overload	Resistance change rate is $\pm (2.0\% + 0.1 \Omega)$ Max.	4.13 Permanent resistance change after the application of a potential of 2.5 times RCWV for 5 seconds				
Solderability	95 % coverage Min.	Wave Solder: Test temperature of solder: 245°C ±3°C dipping time in solder: 2-3 seconds.				
	Go up tin rate bigger than half of end pole.	Refolw: 250 250 230°C				
Soldering Heat	Resistance change rate is: ±(1%+0.05Ω) Max.	4.18 Dip the resistor into a solder bath having a temperature of 260°C±3°C and hold it for 10±1 seconds.				

	Thick Film Chip R	esistor Array (l	Lead Free)				
7. Performano	ce specification:						
Characteristics	Limits	Test Methods (JIS C 5201-1)					
			nce change after continuous duty cycle specified be				
		Step	Temperature	Time			
Temperature	Resistance change rate is	1	-55°C ± 3°C	30 mins			
cycling	$\pm (1.0\% + 0.05 \Omega)$ Max.	2	Room temp.	10∼15 mins			
		3	+155°C ± 2°C	30 mins			
		4	Room temp.	10~15 mins			
			ce change after 1,000				
Load life in	Resistance change rate is	(1.5 hours "d	on", 0.5 hour "off") at	RCWV			
humidity	$\pm (3.0\% + 0.1 \Omega)$ Max.	in a humidit	y chamber controlled a	at			
		$40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ and 90 to 95 % relative humidity					
	Resistance change rate is	4.25.1 Perm	anent resistance chang	e after 1,000 hours			
Load Life	$\pm (3.0\% + 0.1 \Omega)$ Max.	operating at	RCWV, with duty cyc	ele of			
		(1.5 hours"o	on", 0.5 hour"off") at 7	$0^{\circ}\text{C} \pm 2^{\circ}\text{C}$ ambient			
Terminal	Resistance change rate is	4.33 Twist o	of Test Board :				
bending	$\pm (1.0\% + 0.05 \Omega)$ Max.	Y/X = 3/90	mm for 60 seconds				

Thick Film Chip Resistor Array (Terminal Lead Free)

8. Packing specification:

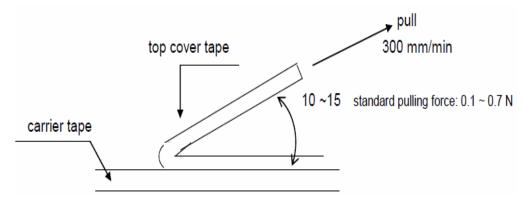
* Taping Dimension (mm)



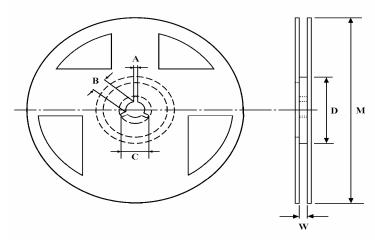
Туре	A ± 0.2	B ± 0.2	$C \pm 0.05$	φD+0.1	E ± 0.1	$F \pm 0.05$	$G \pm 0.1$	W ± 0.2	$T \pm 0.1$
RMC 2D02	1.2	1.2	2.0	1.5	1.75	3.5	4.0	8.0	0.45

* Peeling Strength of Top Cover Tape

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.



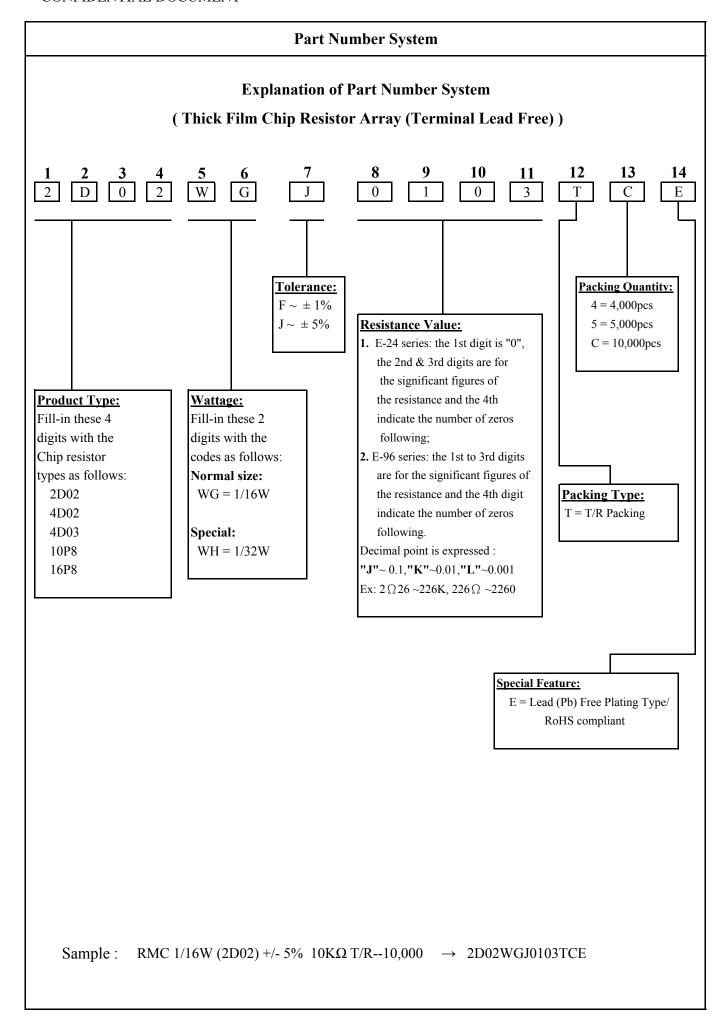
* Reel Dimension (mm)



Туре	Quantity Per Reel	$A \pm 0.5$	$B \pm 0.5$	$C \pm 0.5$	D ± 1	$M \pm 2$	W ± 1
RMC 2D02	10,000 pcs. / Reel	2	13	21	60	178	10

Remark : ϕ M 10,000pcs. / Reel = 255 ± 2mm

20,000pcs. / Reel = 330 ± 2 mm



Thick Film Chip Resistor Arrays (Terminal Lead Free)

Environment Related Substance

This product complies to EU RoHS directive, EU PAHs directive, EU PFOS directive and Halogen free.

Ozone layer depleting substances.

Ozone depleting substances are not used in our manufacturing process of this product.

This product is not manufactured using Chloro fluorocarbons (CFCs), Hydrochlorofluorocarbons (HCFCs),

Hydrobromofluorocarbons (HBFCs) or other ozone depleting substances in any phase of the manufacturing process.

Storage Condition

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ and a relative humidity of $60\%\text{RH} \pm 10\%\text{RH}$

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

1. In salty air or in air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂

Page 8.

2. In direct sunlight